# Monthly LabAdviser update: 14/3 2014

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| Updated Subject  | Contributor | Link to the updated pages |
| **ICP metal** silicon nitride etch test results. | **Izzet Yildiz @Nanotech** | [ICP metal - silicon nitride etch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/silicon_nitride) |
| **Piranha:**Reason for adding hydrogen peroxide to the sulfuric acid, and sulfuric acid to hydrogen peroxide. | **Kristian Hagsted Rasmussen @danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Wafer_cleaning/7-up_%26_Piranha> |
| **SiO2 deposition**Deposition in Lesker has been added to the SiO2 deposition comparison table | **Katharina Nilson @Danchip** | [Lesker in SiO2 deposition comparison table](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide#Comparison_of_the_methods_for_deposition_of_Silicon_Oxide) |
| **Silicon nitride deposition**Deposition in Lesker has been added to the silicon nitride deposition comparison table | **Jesper Hanberg @Danchip** | [Lesker in the Silicon nitride deposition comparison table](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Nitride/Deposition_of_Silicon_Nitride_using_LPCVD) |
| **All metal deposition comparison pages has been updated**-In particular Au and TiW-but also for AlTi, Ni, Cu, Mo, Pd, Ag, Sn, Ta, W, Pt, NiCr and AlTi  | **Katharina Nilson @Danchip** | [Comparison page for deposition of gold](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Gold)[Comparison page for deposition of TiW](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_TiW) |
| **Wafer cleaning**Comparison of the wafer clean procdures and explanation on when to use what. | **Karen Birkelund @Danchip** | [Wafer cleaning](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Wafer_cleaning) |
| **New equipment in pipeline and Old equipment for decommissioning**-Updated page | **Danchip** | [New equipment in the pipeline and Old equipment for decommissioning](http://labadviser.danchip.dtu.dk/index.php/LabAdviser/New_equipment_in_the_pipeline_and_Old_equipment_for_decommissioning) |
| **Lithography Pretreatment**New comparison table and improved equipment describtion | **Thomas Anhøj @Danchip** | [Photolithography Pretreatment](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Pretreatment#HMDS) |
| **Thermal oxidation**Comparison page for the oxidation furnaces has been revised. | **Mikkel D. Mar @Danchip** | [Thermal Oxidation](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/Oxidation) |
| **Dry Etch**Comparison page have a new look. | **Jonas M. Lindhard** | [Comparison page dry etch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Comparison) |
| **Spray coater**Updated equipment page | **Claus H. Nielsen @Danchip** | [SprayCoater](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Coaters/SprayCoater) |
| **Updated equipment pages:**Wet etch AlWet etch PolySiWet etch NitrideIII-V ICPIII-V oven D4IonfabEVG NIL | **Karen****Jonas****Mikkel****Berit****Thomas****@Danchip** |  |